

Bill of Materials

TI DESIGNS

TIDA-00676

Item	Reference	Qty	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	IPC	1		Printed Circuit Board	Any	TIDA-00676			
2	C1	1	100uF	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	MuRata	GRM32ER60J107ME20L		1210	
3	C2, C3, C4	3	10uF	CAP, CERM, 10uF, 6.3V, +/-20%, X5R, 0603	MuRata	GRM188R60J106ME84		0603	
4	C7	1	3000000uF	CAP, Electric Double Layer, 3000000uF, 2.7V, +20/-	NESSCAP	ESHSR-0003C0-002R7		TH, 2-Leads, 8mm	
5	C09, C12, C13	3	100uF	CAP, TA, 100 uF, 16 V, +/- 20%, 0.09 ohm, SMD	Vishay-Sprague	594D107X0016D2T		Case Code D	
6	C10	1	10uF	CAP, CERM, 10 uF, 6.3 V, +/- 20%, X5R, 1206	TDK	C3216X5R0J106M		1206	
7	C11	1	2.2pF	CAP, CERM, 2.2 pF, 50 V, +/- 11%, C0G/NP0, 0805	AVX	08055A2R2CAT2A		0805	
8	J1, J2, J3, J4, J5, J6, J7, J8, J9,	17		Header, TH, 100mil, 2x1, Gold plated, 230 mil above	Samtec, Inc.	TSW-102-07-G-S		TSW-102-07-G-S	
9	J18	1		Connector, 15x2, 3A 300V STRT DIP, TH	Omron Electronic Components	XG4C-3031		Connector, 15x2	
10	JP1, JP2, JP3, JP4, JP5, JP6, JP7,	10		Header, TH, 100mil, 3x1, Gold plated, 230 mil above	Samtec, Inc.	TSW-103-07-G-S		TSW-103-07-G-S	
11	L1	1	2.2uH	Inductor, Multilayer, Ceramic, 2.2uH, 0.7A, 0.23 ohm,	FDK	MIPSZ20120D2R2		2.2x1x1.45 mm	
12	L2	1	6.8uH	Inductor, SMT, yyA, zmmilohm	Sumida	CDRH124-6R8		0.485 sq inch	
13	Q1, Q2	2	-12V	MOSFET, P-CH, -12V, -2.3A, 1.0x0.35x0.6mm	Texas Instruments	CSD23381F4		1.0x0.35x0.6mm	
14	R1	1	1.00Meg	RES, 1.00Meg ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-071ML		0603	
15	R2	1	30	RES, 30 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060330R0JNEA		0603	
16	R3	1	300	RES, 300 ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-07300RL		0603	
17	R4, R5	2	2.7k	RES, 2.7k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06032K70JNEA		0603	
18	U1	1		360mA IQ Step Down Converter for Low Power	Texas Instruments	TPS62740DSS		DSS0012A	
19	U2	1		96% Efficient Synchronous Boost Converter With 4A	Texas Instruments	TPS61030RSAR		RSA0016B	

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